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Quarterly Reliability Monitoring Results

Quarters: Q1/2021 to Q4/2021

Based on structural	similarity
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Supplier		User Part Number					
Nexperia B.V.		PMEG3010EH					
Name of Laboratory Assembly reliability labs Based on AEC-Q101 Test		Part Description					
		Nexperia DHAM	Schottky				
		SMD package					
		Test Conditions	Duration	# Lots	# Quantity	# Rejects	
	TEST Pre- and Post-Stress						
# E1	Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below	
# A1	PC Preconditioning	JESD22-A113 Bake Tamb = 125 °C Soak Tamb = 85 °C, RH = 85% Reflow soldering	24 hours 168 hours 3 cycles	810	58300	0	
# B1	HTRB High Temperature Reverse Bias	MIL-STD-750-1 M1038 Method A Tj = Tjmax, Vr = 100% of max. datasheet reverse voltage ^[1]	1000 hours	116	9280	0	
# A4	TC Temperature Cycling	JESD22-A104 -65 °C to Tjmax, not to exceed 150°C	1000 cycles	170	13600	0	
# A3 alt	AC Autoclave	JESD22-A102 Tamb = 121 °C, RH = 100 % Pressure = 205 kPa (29.7 psia)	96 hours	170	13600	0	
# A2 alt	H3TRB High Humidity High Temperature Reverse Bias	JESD22-A101 Tamb = 85 °C, RH = 85%, VR = 80 % of rated reverse voltage ^{[1], [2]}	1000 hours	170	13600	0	
	IOL	MIL-STD-750 Method 1037 ton = toff, devices powered to insure $\Delta T j$ =					
# A5	Intermittent Operating Life	100 °C for 15000 cycles	1000 hours	170	13600	0	
≠ C8	RSH Resistance to Solder Heat	JESD22-A111 260 °C ± 5 °C	10 s	130	3900	0	
¢ C10	SD Solderability	J-STD-002		363	3630	0	

[1] The physical limitations of Schottky diodes have to be considered (thermal runaway).

[2] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
Nexperia DHAM	Schottky	9280	0	0.46	2.19E+09
010/01	SCHULKY	9280	0	0:46	2.192+09

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